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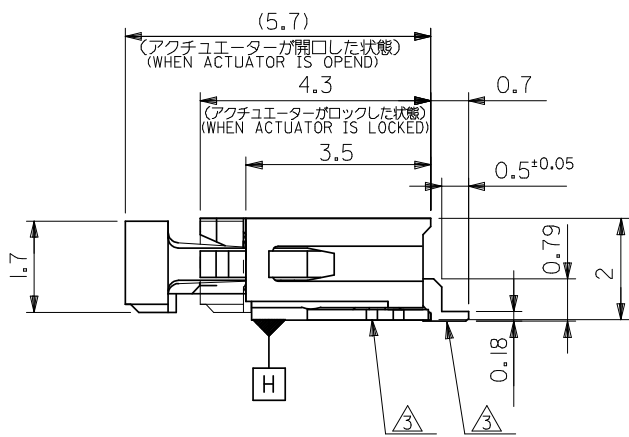
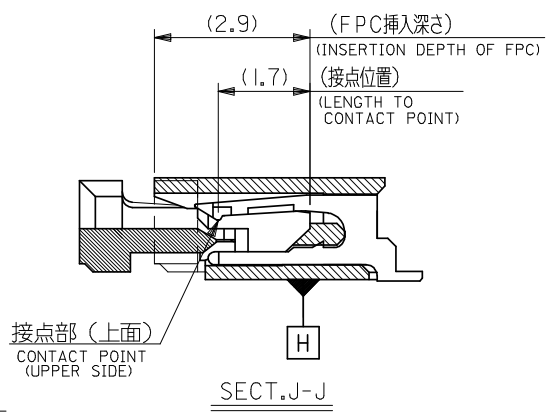
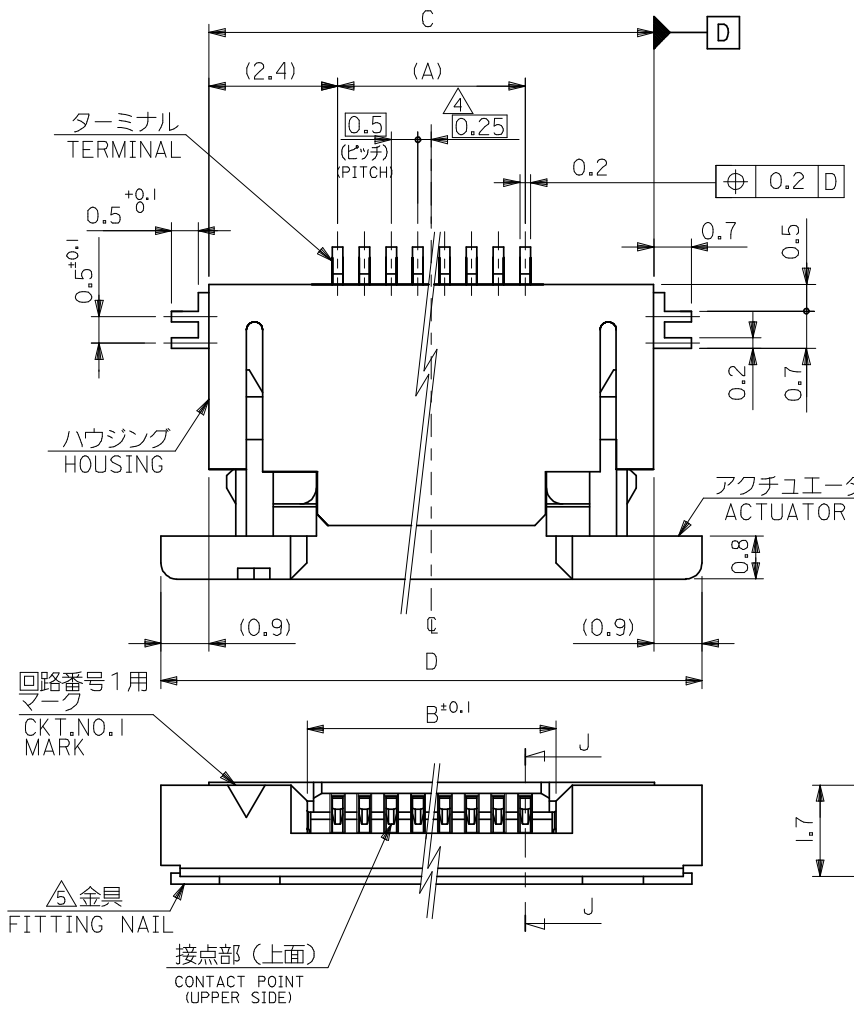
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注記 NOTES

1. 使用材料 MATERIAL
- | | |
|---------------------|--|
| ハウジング
HOUSING | : ポリアミド46、ガラス充填、UL94V-0 (白)
POLYAMIDE46, GLASS FILLED, UL94V-0(WHITE) |
| アクチュエータ
ACTUATOR | : ポリフェニレンサルファイド、ガラス充填、UL94V-0 (黒)
POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0(BLACK) |
| ターミナル
TERMINAL | : リン青銅、ニッケル下地銅ビスマスメッキ (t=0.2)
PHOSPOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING |
| 金具
FITTING NAIL | : リン青銅、ニッケル下地純銅メッキ (t=0.2)
PHOSPOR BRONZE, TIN OVER NICKEL PLATING |
2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 52745-**19 SHOULD BE LOCKED.
- △ ソルダテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX. 下方向 0.15 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM H UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. 本製品は 52745-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52745-**17

16.1	14.3	10.65	9.5	52745-2096	52745-2019	20
15.6	13.8	10.15	9.0	-1996	-1919	19
15.1	13.3	9.65	8.5	-1896	-1819	18
14.6	12.8	9.15	8.0	-1796	-1719	17
14.1	12.3	8.65	7.5	-1696	-1619	16
13.6	11.8	8.15	7.0	-1596	-1519	15
13.1	11.3	7.65	6.5	-1496	-1419	14
12.6	10.8	7.15	6.0	-1396	-1319	13
12.1	10.3	6.65	5.5	-1296	-1219	12
11.6	9.8	6.15	5.0	-1196	-1119	11
11.1	9.3	5.65	4.5	-1096	-1019	10
10.6	8.8	5.15	4.0	-0996	-0919	9
10.1	8.3	4.65	3.5	-0896	-0819	8
9.6	7.8	4.15	3.0	-0796	-0719	7
9.1	7.3	3.65	2.5	-0696	-0619	6
8.1	6.3	2.65	1.5	52745-0496	52745-0419	4
D	C	B	(A)	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	極数 CIRCUIT

52745-**19 | MODEL NO.

REVISED EC NO: J2008-4308 DRWN: WABEI CHKD: THARUYAMA APPR: NUKITA B	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30 REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION				
		10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/01/28	TITLE 0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE-						
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/01/28							
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/01/28	 MOLEX INCORPORATED						
		ANGULAR ±3 °		MATERIAL NO. SEE TABLE					DOCUMENT NO. SD-52745-048		SHEET NO. 1 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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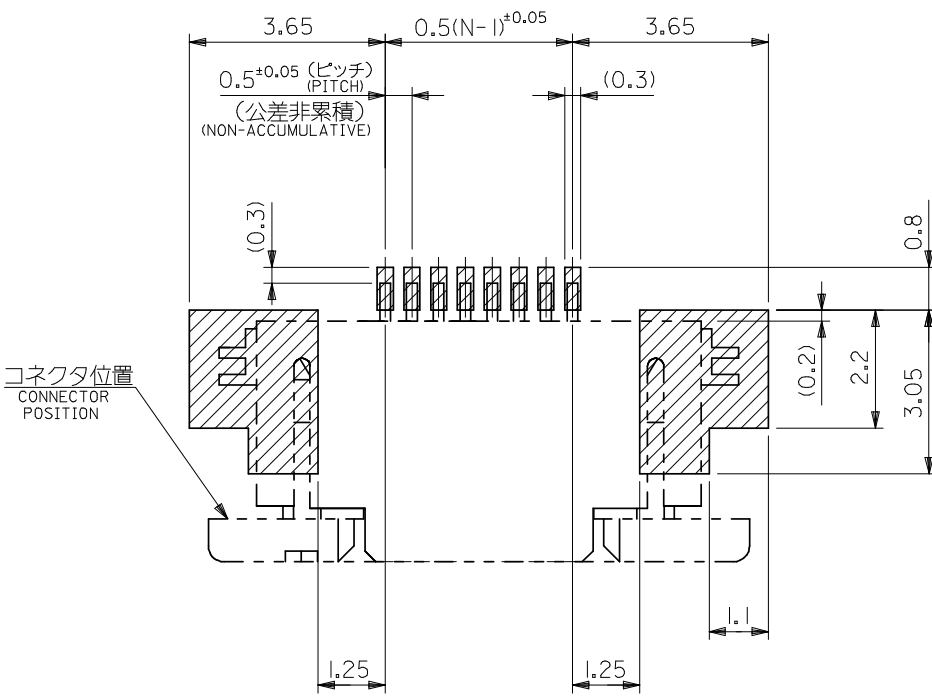
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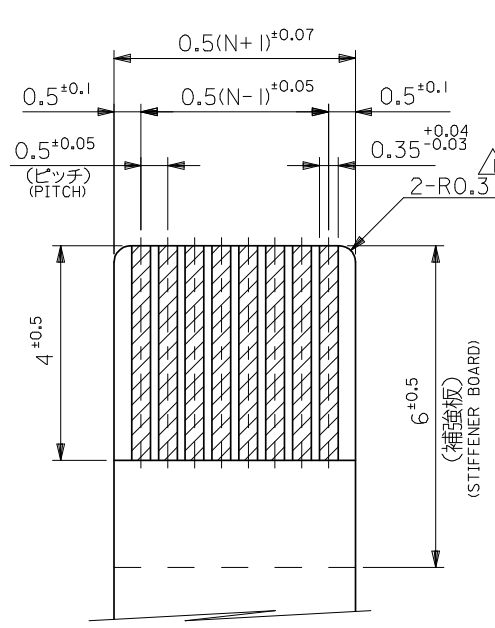
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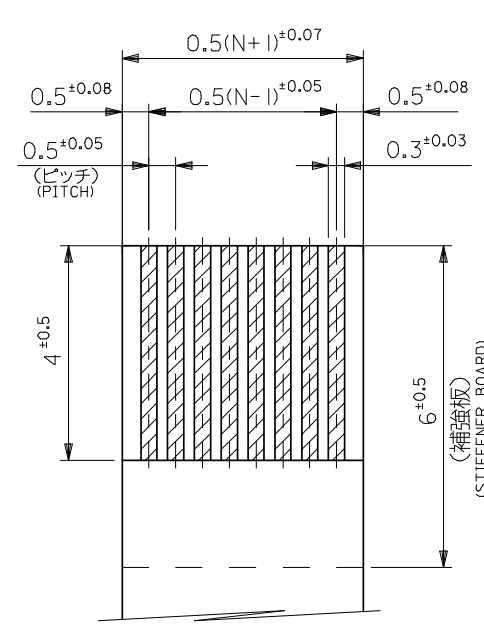
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参考基板レイアウト
P.C. BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

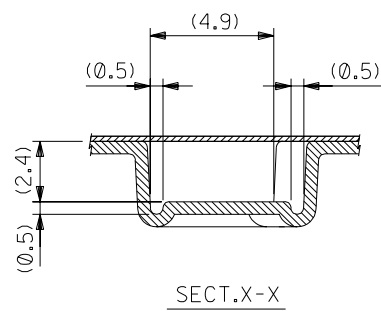
注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

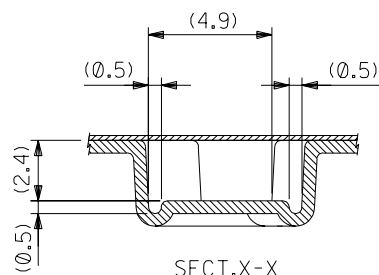
ABOUT FPC :
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED		EC NO: J2008-4308		2008/06/27		DRWN:WABEI		2008/06/30		CHKD:THARUYAMA		2008/06/30		APPR:NUKITA		2008/06/30		DESCRIPTION		REV	
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION		MODEL NO.		52745-**19		TITLE		SHEET NO.		2 OF 2		EN-02JA(021)	
10 UNDER		±0.2		DRAWN BY		DATE		T. UENO		'04/01/28		0.5 FPC CONN ASSY ZIF		UPR CONT		-LEAD FREE-		MOLEX INCORPORATED		SD-52745-048	
10 OVER 30 UNDER		±0.25		CHECKED BY		DATE		M. SASAO		'04/01/28		MOLEX INCORPORATED		SD-52745-048		2 OF 2		EN-02JA(021)		EN-02JA(021)	
30 OVER		±0.3		APPROVED BY		DATE		M. SASAO		'04/01/28		MOLEX INCORPORATED		SD-52745-048		2 OF 2		EN-02JA(021)		EN-02JA(021)	
ANGULAR		±3 °		MATERIAL NO.		DOCUMENT NO.		SEE SHEET 1		SD-52745-048		MOLEX INCORPORATED		SD-52745-048		2 OF 2		EN-02JA(021)		EN-02JA(021)	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		A3		SEE SHEET 1		SD-52745-048		MOLEX INCORPORATED		SD-52745-048		2 OF 2		EN-02JA(021)		EN-02JA(021)	



DRAWN BY & DATE T.UENO '04/01/08		TITLE: 0.5 FPC Conn Assy ZIF for SMT RA Embstp Pkg -LEAD FREE-		
CHECKED BY & DATE M.SASAO '04/01/08				
APPROVED BY & DATE M.SASAO '04/01/08		MOLEX INCORPORATED		
CAD FILENAME SD-52745-049.S02	MATERIAL NO. SEE CHART	DRAWING NO. SD-52745-049	SHEET NO. 2 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B

	163NO. DRWN: CHK: APPR:	163NO. DRWN: CHK: APPR:	163NO. DRWN: CHK: APPR:	REVISED 163NO. J2004-2746 DRWN: M.NINOMIYA CHK: K.TOJO APPR: M.SASAO	RELEASED 163NO. J2004-1852 DRWN: T.UENO CHK: M.SASAO APPR: M.SASAO	MATERIAL 材料 SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3
						FINISH 仕上付 
						WIRE RANGE 適用電線範圍 
				A	Ø	REV INS. RANGE 被覆外径 



24	29.4	25.4	17.4	10.8	16.4	52745-2096	20
			16.9	10.3	15.9	- 1996	19
			16.4	9.8	15.4	- 1896	18
			15.9	9.3	14.9	- 1796	17
			15.4	8.8	14.4	- 1696	16
			14.9	8.3	13.9	- 1596	15
			14.4	7.8	13.4	- 1496	14
			13.9	7.3	12.9	- 1396	13
			13.4	6.8	12.4	- 1296	12
			12.9	6.3	11.9	- 1196	11
			12.4	5.8	11.4	- 1096	10
			11.9	5.3	10.9	- 0996	9
			11.4	4.8	10.4	- 0896	8
			10.9	4.3	9.9	- 0796	7
10.4	3.8	9.4	52745-0696	6			
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

[illegible]